# Low V<sub>CE(sat)</sub> NPN Transistors, 60 V, 1 A

# **NSS60101DMR6**

ON Semiconductor's  $e^2$ PowerEdge family of low  $V_{CE(sat)}$  transistors are miniature surface mount devices featuring ultra low saturation voltage ( $V_{CE(sat)}$ ) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC-DC converters and LED lightning, power management...etc. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e<sup>2</sup>PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

#### **Features**

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### **MAXIMUM RATINGS** (T<sub>A</sub> = 25°C)

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	60	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	80	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	6	Vdc
Collector Current - Continuous	I <sub>C</sub>	1	Α
Collector Current - Peak	I <sub>CM</sub>	2	Α

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

# THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance Junction-to-Ambient (Notes 1 and 2)	$R_{\theta JA}$	234	°C/W
Total Power Dissipation per Package @ T <sub>A</sub> = 25°C (Note 2)	P <sub>D</sub>	0.53	W
Thermal Resistance Junction-to-Ambient (Note 3)	$R_{\theta JA}$	300	°C/W
Power Dissipation per Transistor @ T <sub>A</sub> = 25°C (Note 3)	P <sub>D</sub>	0.40	W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

- 1. Per JESD51-7 with 100 mm<sup>2</sup> pad area and 2 oz. Cu (Dual Operation).
- 2. P<sub>D</sub> per Transistor when both are turned on is one half of Total P<sub>D</sub> or 0.53 Watts.
- 3. Per JESD51-7 with 100 mm<sup>2</sup> pad area and 2 oz. Cu (Single-Operation).



# ON Semiconductor®

www.onsemi.com

60 Volt, 1 Amp NPN Low  $V_{CE(sat)}$  Transistors



SC-74 CASE 318F



**MARKING** 

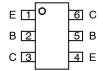
RAD = Specific Device Code

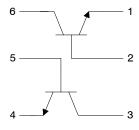
M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

#### **PIN CONNECTIONS**





#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>	
NSS60101DMR6T1G			
NSS60101DMR6T2G	SC-74	3000/Tape &	
NSV60101DMR6T1G	(Pb-Free)	Reel	
NSV60101DMR6T2G			

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

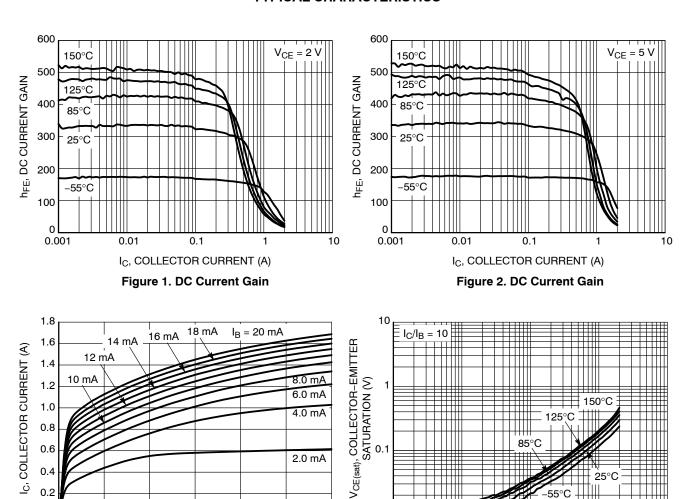
Table 1. ELECTRICAL CHARACTERISTICS ( $T_A = 25^{\circ}C$  unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector-Emitter Breakdown Voltage (I <sub>C</sub> = 10 mA, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	60			V
Collector-Base Breakdown Voltage (Ic = 0.1 mA, I <sub>E</sub> = 0)	V <sub>(BR)CBO</sub>	80			٧
Emitter-Base Breakdown Voltage ( $I_E = 0.1 \text{ mA}, I_C = 0$ )	V <sub>(BR)EBO</sub>	6			V
Collector Cutoff Current (V <sub>CB</sub> = 60 V, I <sub>E</sub> = 0)	I <sub>CBO</sub>			100	nA
Emitter Cutoff Current (V <sub>BE</sub> = 5.0 V)	I <sub>EBO</sub>			100	nA
ON CHARACTERISTICS	•		<u> </u>		ı
DC Current Gain (Note 4) (I <sub>C</sub> = 100 mA, V <sub>CE</sub> = 2 V)	h <sub>FE</sub>	200	320		
$(I_C = 500 \text{ mA}, V_{CE} = 2 \text{ V})$ $(I_C = 1 \text{ A}, V_{CE} = 2 \text{ V})$ $(I_C = 1 \text{ mA}, V_{CE} = 5 \text{ V})$ $(I_C = 100 \text{ mA}, V_{CE} = 5 \text{ V})$		150 70 250 250	290 110 335 335		
$(I_C = 500 \text{ mA}, V_{CE} = 5 \text{ V})$ $(I_C = 1 \text{ A}, V_{CE} = 5 \text{ V})$	V	200 100	310 295		\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
Collector–Emitter Saturation Voltage (Note 4) ( $I_C$ = 100 mA, $I_B$ = 1 mA) ( $I_C$ = 500 mA, $I_B$ = 50 mA) ( $I_C$ = 1 A, $I_B$ = 50 mA) ( $I_C$ = 1 A, $I_B$ = 100 mA)	V <sub>CE</sub> (sat)		0.080 0.078 0.170 0.143	0.200 0.150 0.250 0.200	V
Base – Emitter Saturation Voltage (Note 4) $ (I_C = 500 \text{ mA}, I_B = 50 \text{ mA}) $ $ (I_C = 1 \text{ A}, I_B = 50 \text{ mA}) $ $ (I_C = 1 \text{ A}, I_B = 100 \text{ mA}) $	V <sub>BE(sat)</sub>		0.87 0.91 0.94	1.50 1.50 1.60	V
Base-Emitter Turn-on Voltage (Note 4) (I <sub>C</sub> = 1 mA, V <sub>CE</sub> = 1 V) (I <sub>C</sub> = 500 mA, V <sub>CE</sub> = 2 V)	V <sub>BE(on)</sub>	0.27	0.57 0.76	0.90	V
DYNAMIC CHARACTERISTICS					
Input Capacitance (V <sub>EB</sub> = 1 V, f = 1.0 MHz)	C <sub>ibo</sub>		100		pF
Output Capacitance (V <sub>CB</sub> = 10 V, f = 1.0 MHz)	C <sub>obo</sub>		8.0		pF
Cutoff Frequency ( $I_C = 50 \text{ mA}$ , $V_{CE} = 2.0 \text{ V}$ , $f = 100 \text{ MHz}$ )	f <sub>T</sub>		200		MHz
SWITCHING TIMES			•	•	•
Delay Time ( $V_{CC}$ = 10 V, $I_{C}$ = 0.5 A, $I_{B1}$ = 25 mA, $I_{B2}$ = -25 mA)	t <sub>d</sub>		10		ns
ON Time ( $V_{CC} = 10 \text{ V}, I_{C} = 0.5 \text{ A}, I_{B1} = 25 \text{ mA}, I_{B2} = -25 \text{ mA}$ )	t <sub>on</sub>		28		ns
Rise Time ( $V_{CC}$ = 10 V, $I_{C}$ = 0.5 A, $I_{B1}$ = 25 mA, $I_{B2}$ = -25 mA)	t <sub>r</sub>		18		ns
Storage Time ( $V_{CC} = 10 \text{ V}, I_C = 0.5 \text{ A}, I_{B1} = 25 \text{ mA}, I_{B2} = -25 \text{ mA}$ )	t <sub>s</sub>		622		ns
OFF Time ( $V_{CC}$ = 10 V, $I_{C}$ = 0.5 A, $I_{B1}$ = 25 mA, $I_{B2}$ = -25 mA)	t <sub>off</sub>		709		ns
Fall Time (V <sub>CC</sub> = 10 V, I <sub>C</sub> = 0.5 A, I <sub>B1</sub> = 25 mA, I <sub>B2</sub> = -25 mA)	t <sub>f</sub>		87		ns
Product parametric performance is indicated in the Electrical Characteris		est conditions	unless othe	rwise noted	l Product

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulse Condition: Pulse Width = 300 μsec, Duty Cycle ≤ 2%.

#### **TYPICAL CHARACTERISTICS**



V<sub>CE</sub>, COLLECTOR EMITTER VOLTAGE (V) Figure 3. Collector Current as a Function of **Collector Emitter Voltage** 

3

0.2

0

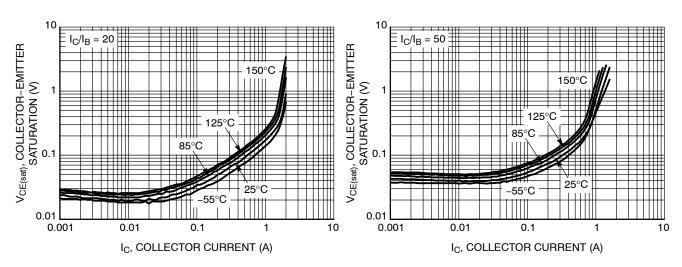
0

IC, COLLECTOR CURRENT (A) Figure 4. Collector-Emitter Saturation Voltage

0.1

25°C

10



0.01

0.001

Figure 5. Collector-Emitter Saturation Voltage

Figure 6. Collector-Emitter Saturation Voltage

### **TYPICAL CHARACTERISTICS**

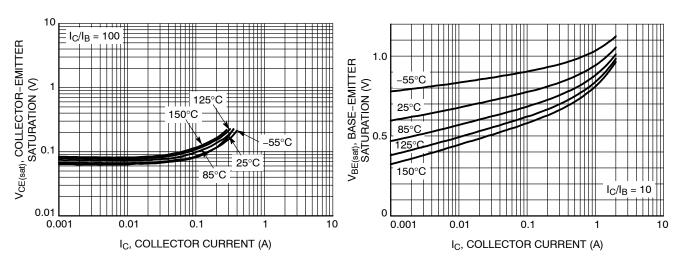


Figure 7. Collector-Emitter Saturation Voltage

Figure 8. Base-Emitter Saturation Voltage

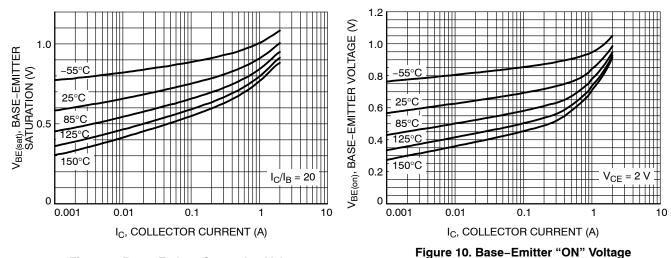


Figure 9. Base-Emitter Saturation Voltage

240 40  $T_A = 25^{\circ}C$ Cobo, OUTPUT CAPACITANCE (pF)  $T_A = 25^{\circ}C$ f = 1 MHz 35 f = 1 MHz C<sub>ibo</sub>, INPUT CAPACITANCE (pF) 200 30 25 160 20 120 15 10 80 5 40 0 10 30 V<sub>EB</sub>, BASE-EMITTER VOLTAGE (V) V<sub>CB</sub>, COLLECTOR-BASE REVERSE VOLTAGE (V) Figure 11. Input Capacitance Figure 12. Output Capacitance

### **TYPICAL CHARACTERISTICS**

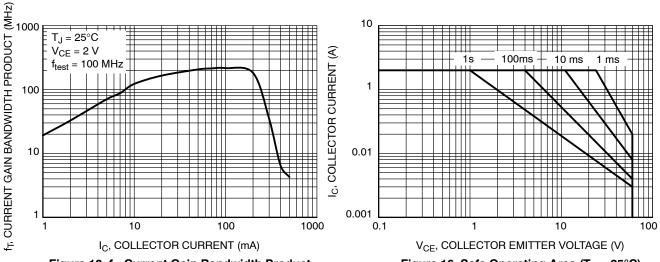


Figure 13. f<sub>T</sub>, Current Gain Bandwidth Product

Figure 16. Safe Operating Area  $(T_A = 25^{\circ}C)$ 

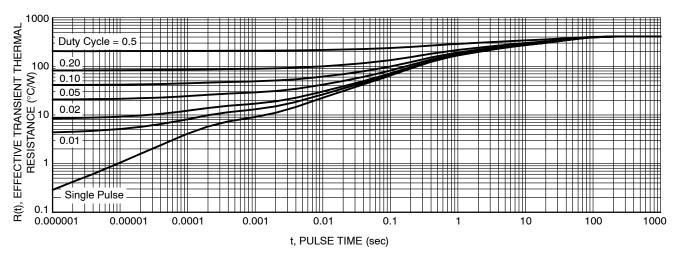


Figure 14. Thermal Resistance by Transistor

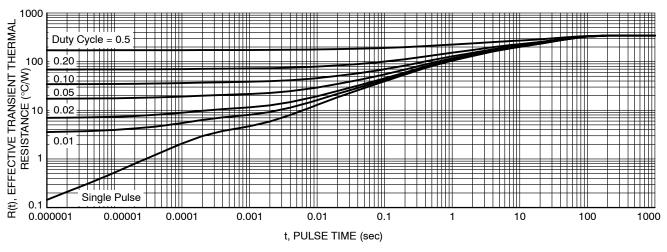


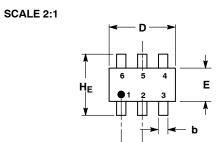
Figure 15. Thermal Resistance for Both Transistors

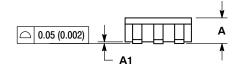
# **MECHANICAL CASE OUTLINE**

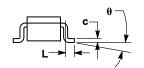


SC-74 CASE 318F-05 **ISSUE N** 

**DATE 08 JUN 2012** 





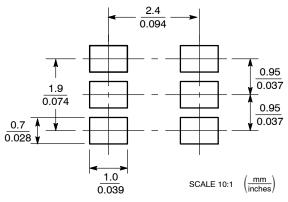


#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH
- 2. CONTROLLING DIMENSION: INCH.
  3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH
  THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
  4. 318F-01, -02, -03, -04 OBSOLETE. NEW STANDARD 318F-05.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.90	1.00	1.10	0.035	0.039	0.043
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.25	0.37	0.50	0.010	0.015	0.020
С	0.10	0.18	0.26	0.004	0.007	0.010
D	2.90	3.00	3.10	0.114	0.118	0.122
E	1.30	1.50	1.70	0.051	0.059	0.067
е	0.985	0.95	11.05	0.084	0.037	0.10241
L	0.20	0.40	0.60	0.008	0.016	0.024
HE	2.50	2.75	3.00	0.099	0.108	0.118
θ		-			-	

# **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

5. BASE 1 6. COLLECTOR 1

# **GENERIC MARKING DIAGRAM\***



XXX = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

5. CATHODE

STYLE 2:	STYLE 3:	STYLE 4:	STYLE 5:	STYLE 6:
PIN 1. NO CONNECTION	PIN 1. EMITTER 1	PIN 1. COLLECTOR 2	PIN 1. CHANNEL 1	PIN 1. CATHODE
2. COLLECTOR	2. BASE 1	2. EMITTER 1/EMITTER 2	2. ANODE	<ol><li>ANODE</li></ol>
<ol><li>EMITTER</li></ol>	<ol><li>COLLECTOR 2</li></ol>	<ol><li>COLLECTOR 1</li></ol>	<ol><li>CHANNEL 2</li></ol>	<ol><li>CATHODE</li></ol>
<ol><li>NO CONNECTION</li></ol>	4. EMITTER 2	4. EMITTER 3	<ol><li>CHANNEL 3</li></ol>	<ol><li>CATHODE</li></ol>
<ol><li>COLLECTOR</li></ol>	5. BASE 2	<ol><li>BASE 1/BASE 2/COLLECTOR 3</li></ol>	<ol><li>CATHODE</li></ol>	<ol><li>CATHODE</li></ol>
6. BASE	<ol><li>COLLECTOR 1</li></ol>	6. BASE 3	<ol><li>CHANNEL 4</li></ol>	<ol><li>CATHODE</li></ol>
STYLE 8:	STYLE 9:	STYLE 10:	STYLE 11:	
PIN 1. EMITTER 1	PIN 1. EMITTER 2	PIN 1. ANODE/CATHODE	PIN 1. EMITTER	
2. BASE 2	2. BASE 2	2. BASE	2. BASE	
<ol><li>COLLECTOR 2</li></ol>	<ol><li>COLLECTOR 1</li></ol>	3. EMITTER	<ol><li>ANODE/CATHOD</li></ol>	Œ
4. EMITTER 2	4. EMITTER 1	4. COLLECTOR	4. ANODE	
	PIN 1. NO CONNECTION 2. COLLECTOR 3. EMITTER 4. NO CONNECTION 5. COLLECTOR 6. BASE  STYLE 8: PIN 1. EMITTER 1 2. BASE 2 3. COLLECTOR 2	PIN 1. NO CONNECTION 2. COLLECTOR 3. EMITTER 4. NO CONNECTION 5. COLLECTOR 6. BASE  STYLE 8: PIN 1. EMITTER 1 2. BASE 2 3. COLLECTOR 2 4. EMITTER 2 5. BASE 2 6. COLLECTOR 1  STYLE 9: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 2 3. COLLECTOR 1	PIN 1. NO CONNECTION	PIN 1. NO CONNECTION         PIN 1. EMITTER 1         PIN 1. COLLECTOR 2         PIN 1. CHANNEL 1           2. COLLECTOR         2. BASE 1         2. EMITTER 1/EMITTER 2         2. ANODE           3. EMITTER         3. COLLECTOR 2         3. COLLECTOR 1         3. CHANNEL 2           4. NO CONNECTION         4. EMITTER 2         4. EMITTER 3         4. CHANNEL 3           5. COLLECTOR         5. BASE 2         5. BASE 1/BASE 2/COLLECTOR 3         5. CATHODE           6. BASE         6. COLLECTOR 1         6. BASE 3         6. CHANNEL 4           STYLE 9:         STYLE 10:         STYLE 11:           PIN 1. EMITTER 1         PIN 1. EMITTER 2         PIN 1. ANODE/CATHODE         PIN 1. EMITTER 2           2. BASE 2         2. BASE 2         2. BASE 2         2. BASE 3           3. COLLECTOR 2         3. COLLECTOR 1         3. EMITTER 3         3. ANODE/CATHODE

5. BASE 1 6. COLLECTOR 2

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DESCRIPTION:	SC-74		PAGE 1 OF 1

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